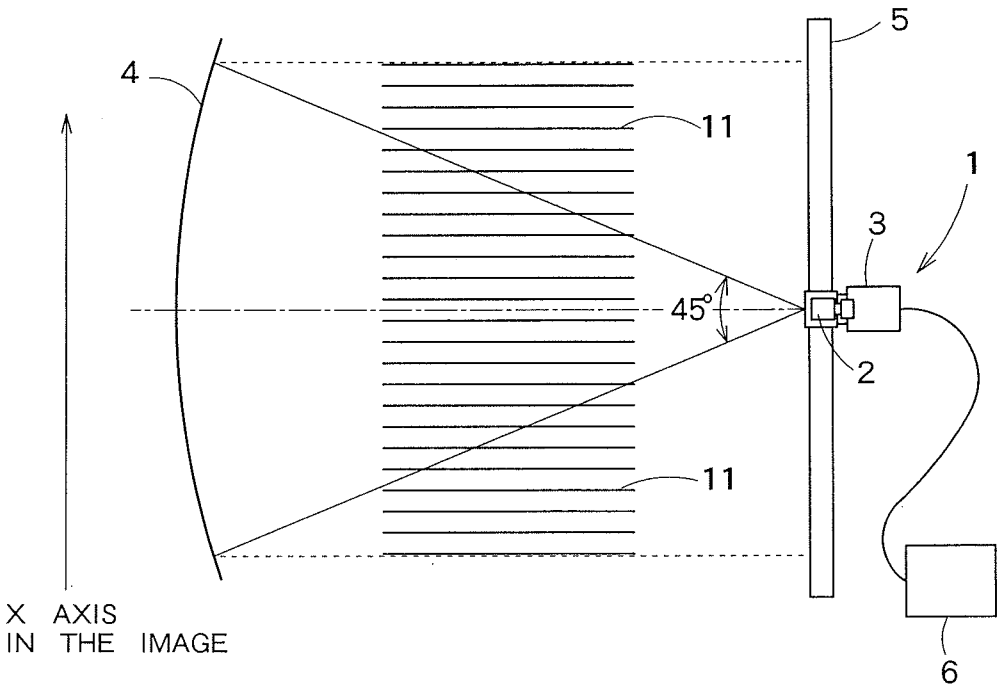

5
4
11
1
3
45°
2
11
X AXIS
IN THE IMAGE
6

FIG. 1A

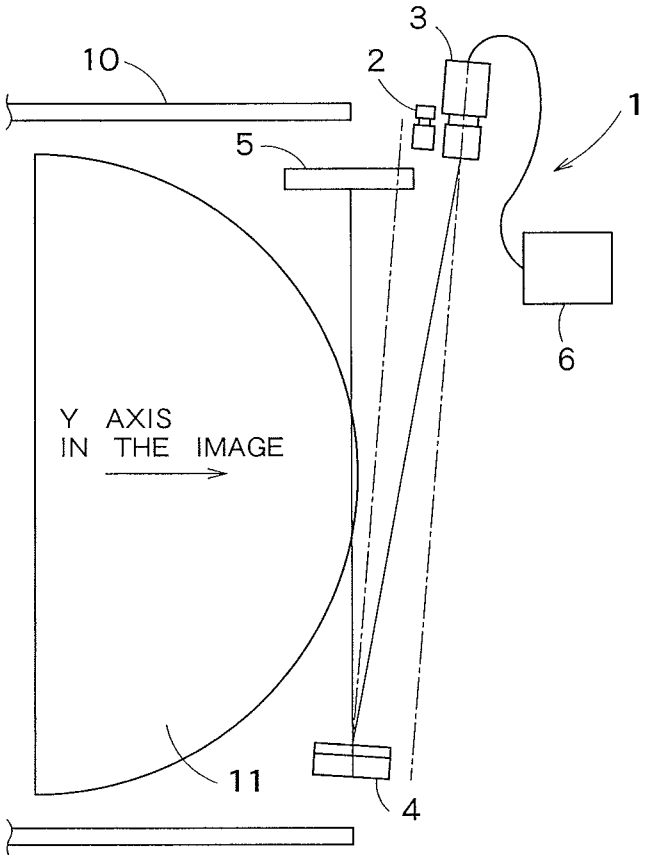

3
10
2
1
5
6
Y AXIS
IN THE IMAGE
11
4

FIG. 1B

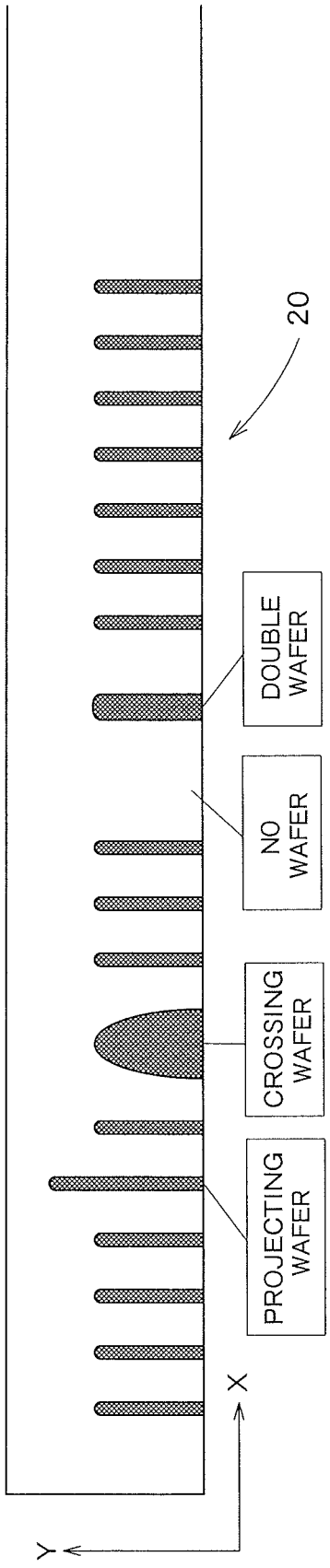

20
DOUBLE WAFER
NO WAFER
CROSSING WAFER
PROJECTING WAFER
X
Y

FIG. 2

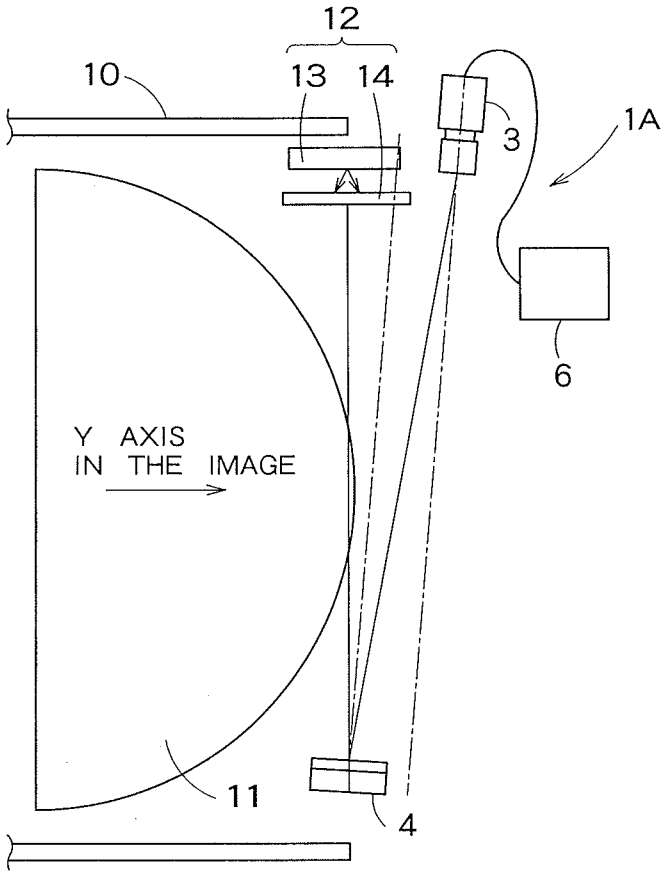

12
10
13
14
3
1A
6
Y AXIS
IN THE IMAGE
11
4

FIG. 3

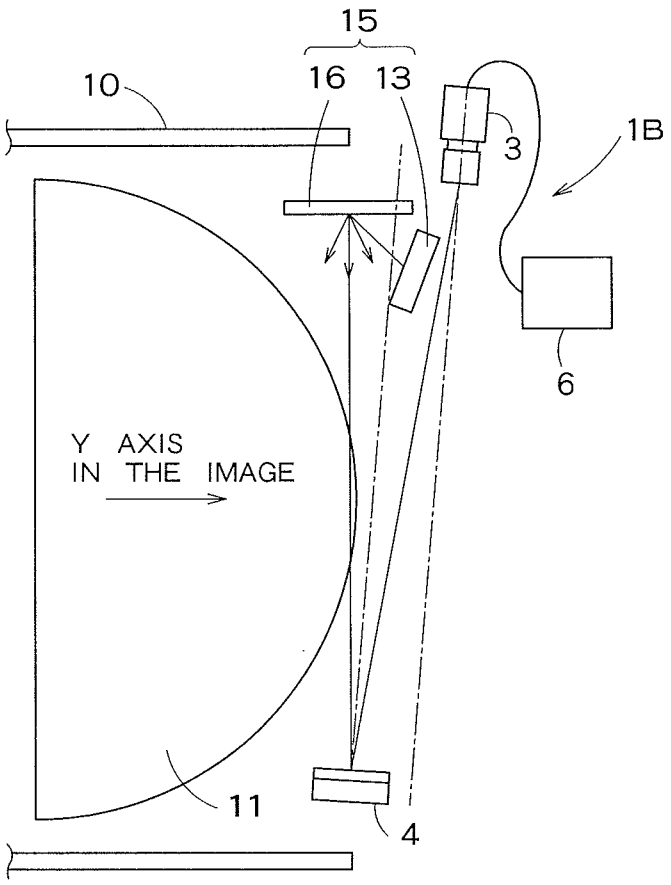

15
10
16
13
3
1B
6
Y AXIS
IN THE IMAGE
11
4

FIG. 4

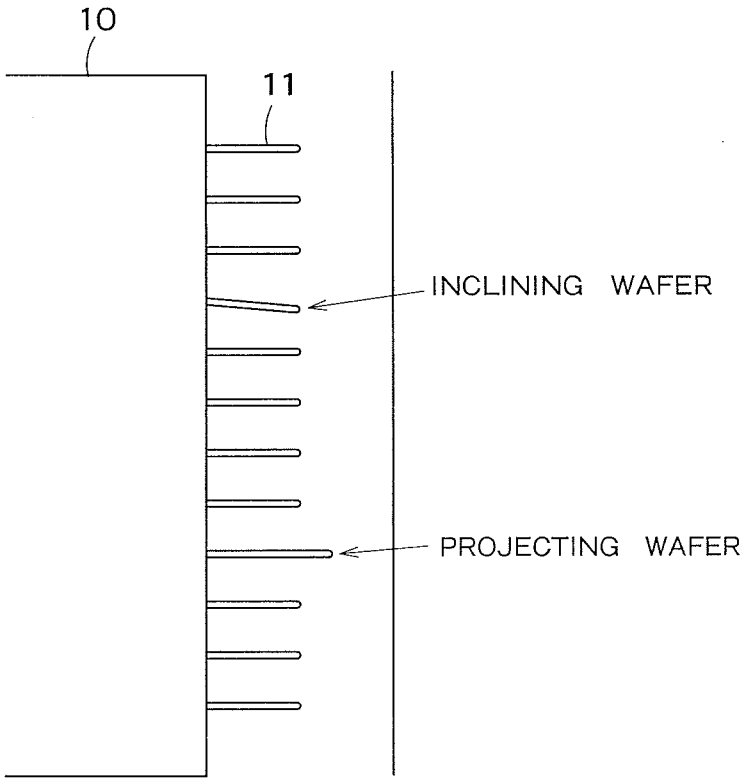

10
11
INCLINING WAFER
PROJECTING WAFER

FIG. 5

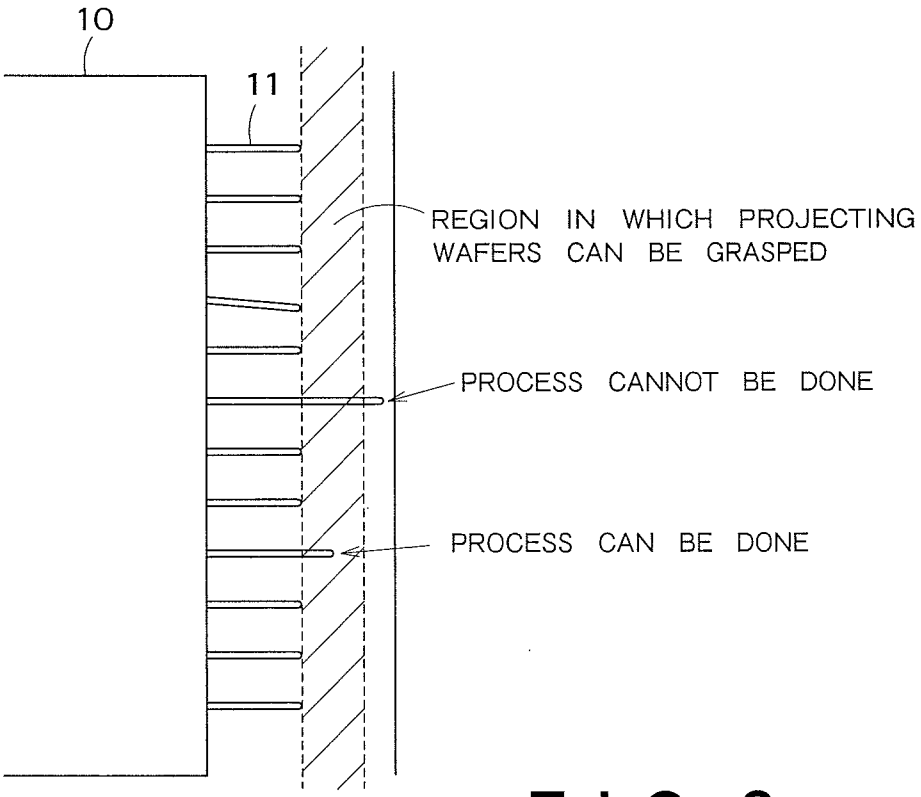

10
11
REGION IN WHICH PROJECTING WAFERS CAN BE GRASPED
PROCESS CANNOT BE DONE
PROCESS CAN BE DONE

FIG. 6

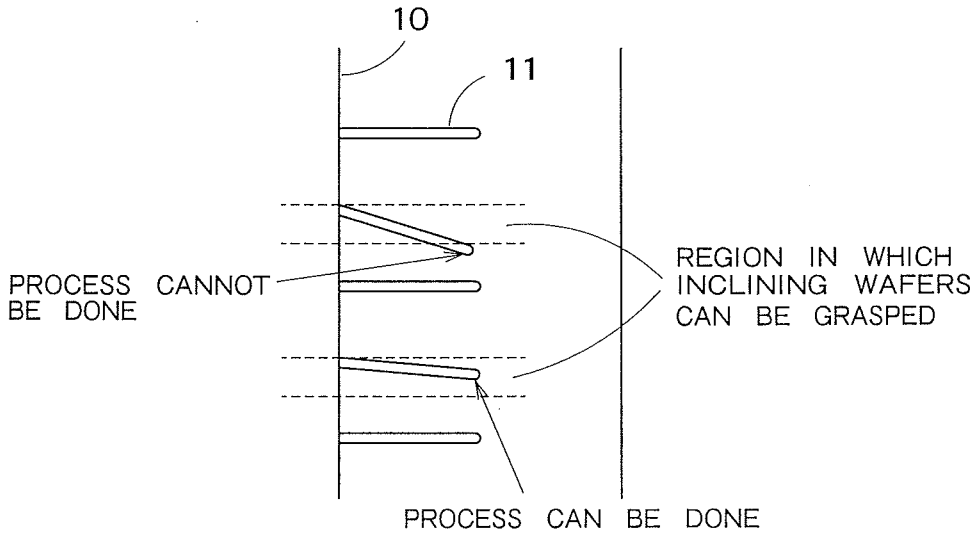

10
11
PROCESS CANNOT BE DONE
REGION IN WHICH INCLINING WAFERS CAN BE GRASPED
PROCESS CAN BE DONE

FIG. 7

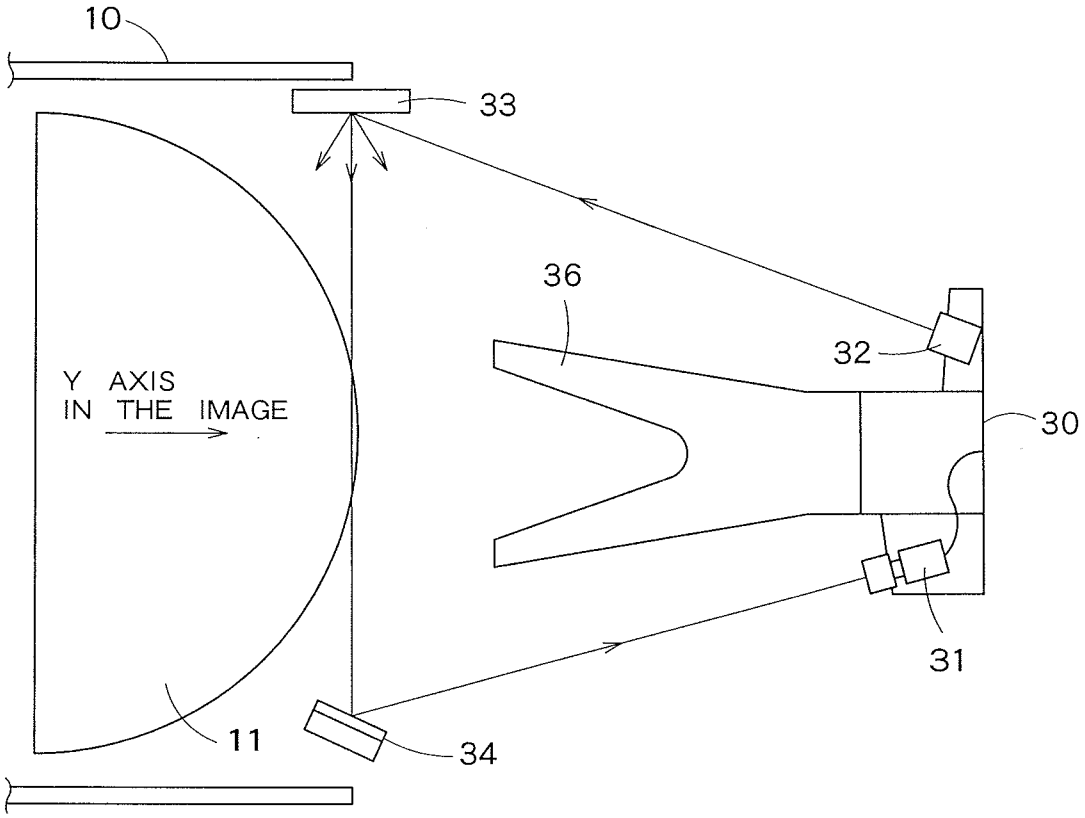

10
33
36
32
30
Y AXIS IN THE IMAGE
31
11
34

FIG. 8

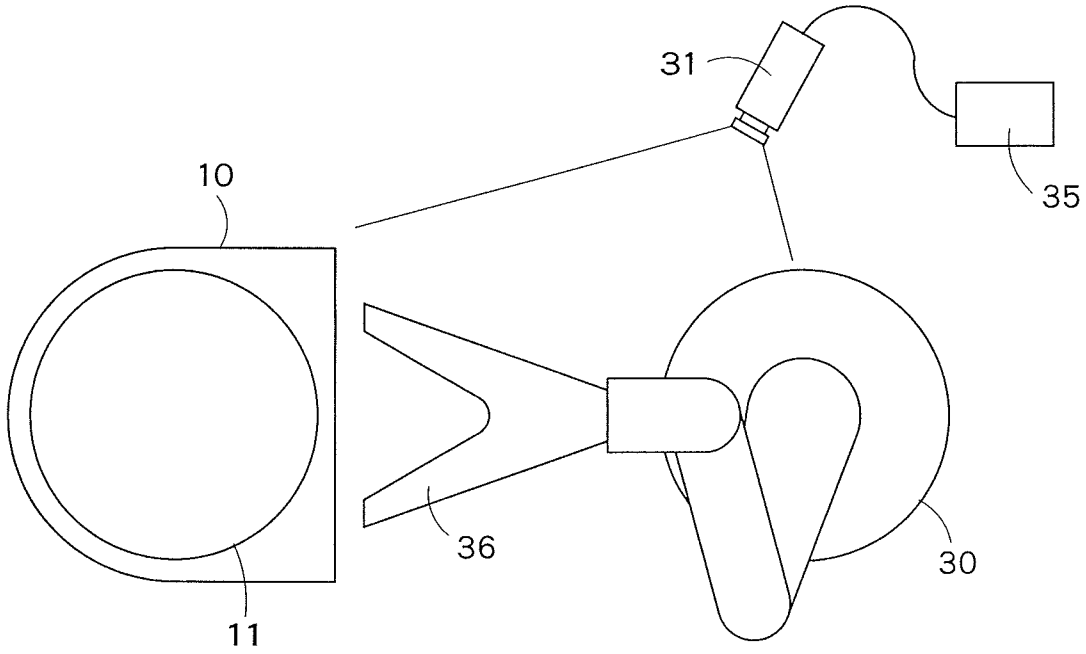


FIG. 9

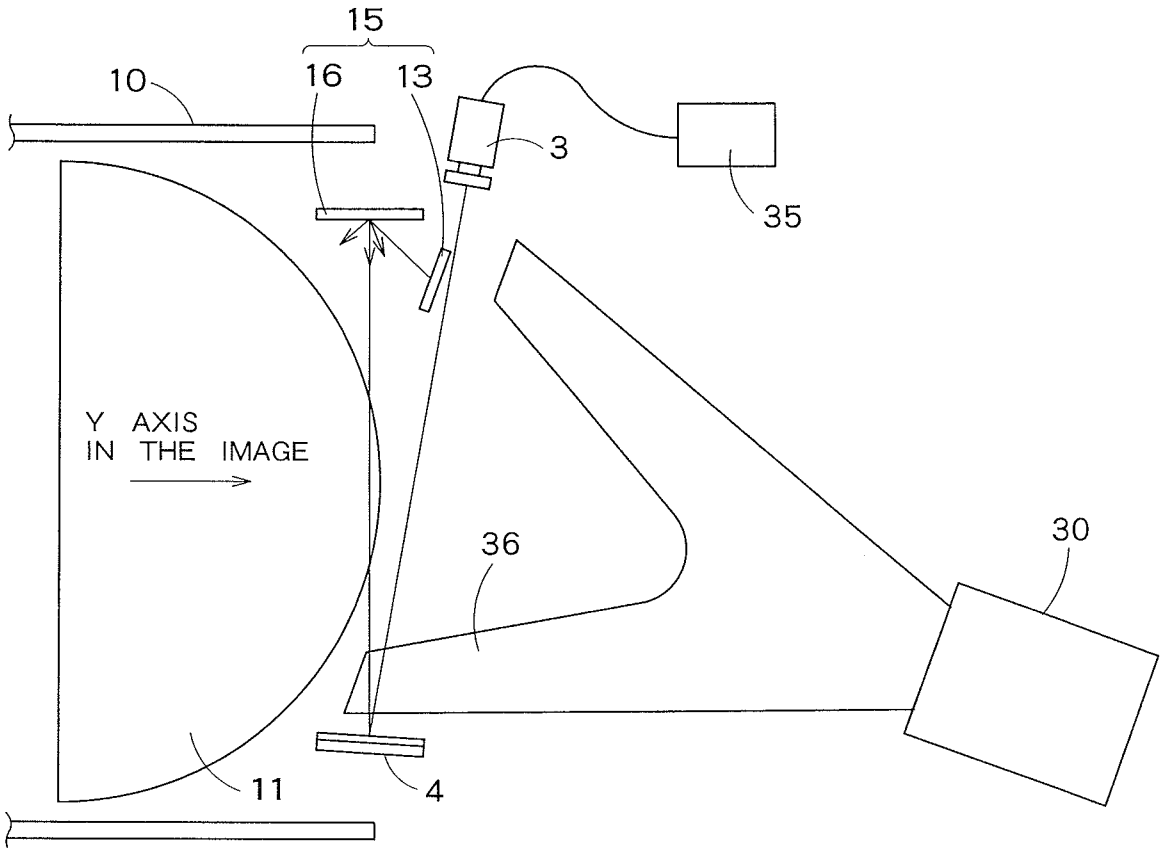


FIG. 10